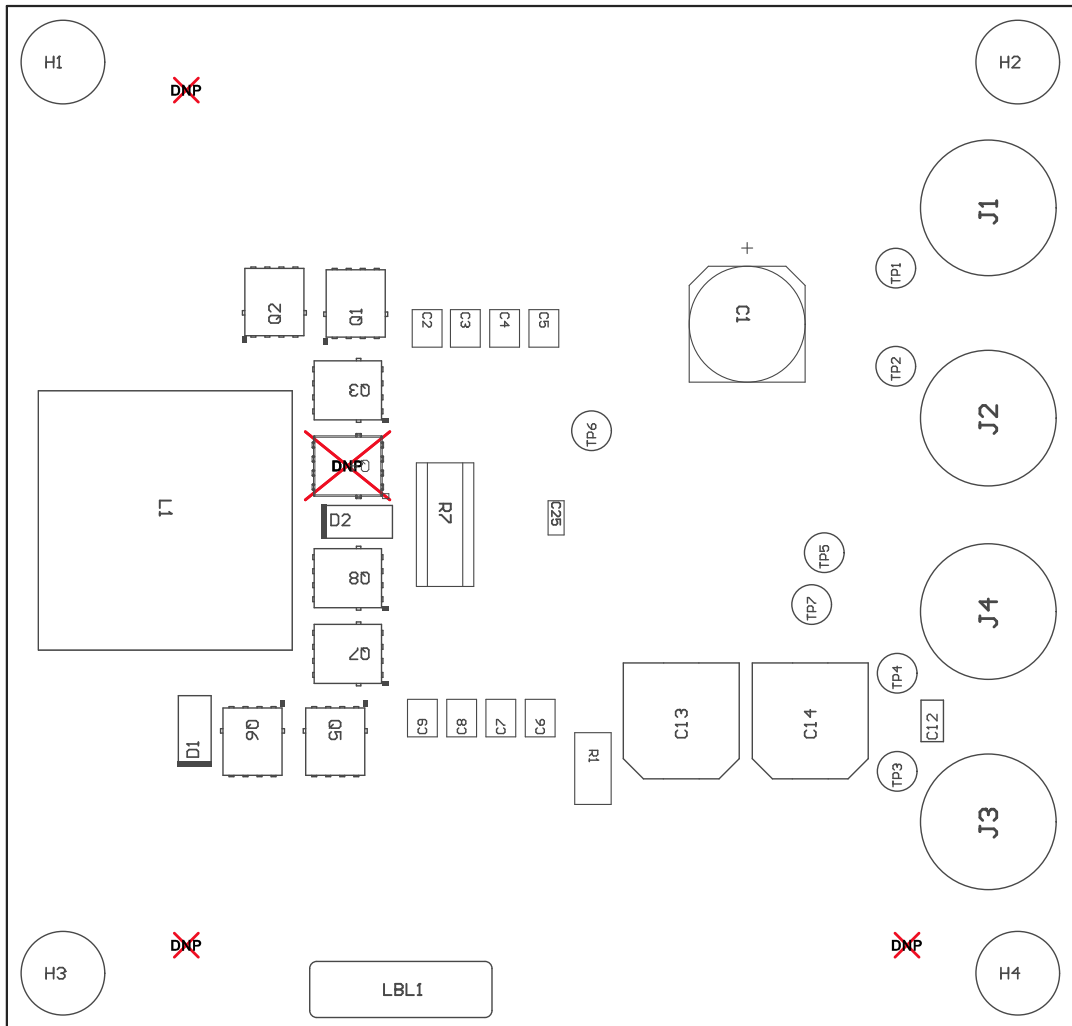
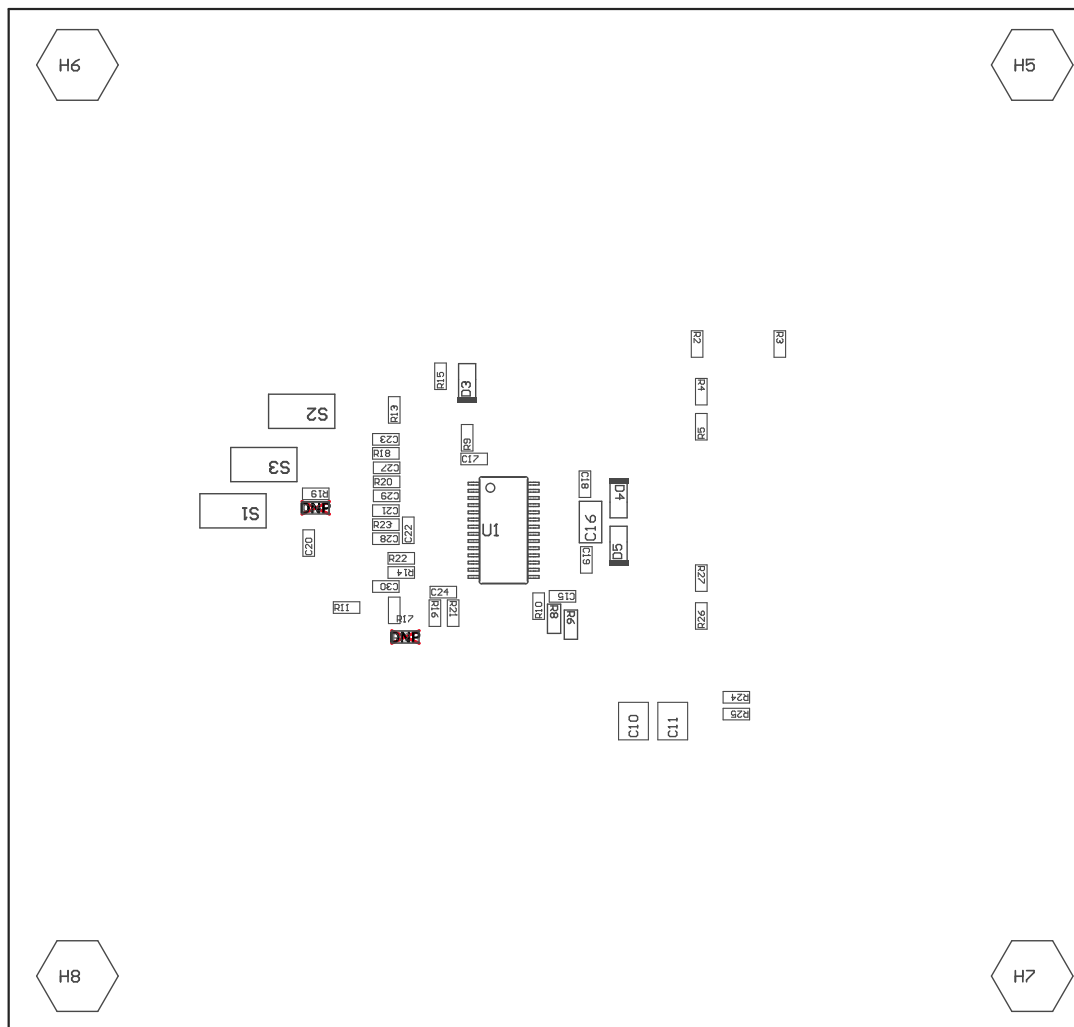


- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- Z25 ■ Remove Kapton tape from switches S1 thru S3 on PCB Bottom side after final wash.
- Z26 ■ Set S1 switch to 'CCM' position as per silkscreen label
- Z27 ■ Set S2 switch to Center position
- Z28 ■ Set S3 switch to 'OFF' position per silk screen label.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Top Assembly Drawing	GENERATED : 11/28/2017 2:31:46 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20660	REV:	SUN REV: Not In VersionControl
	IGNORE ->		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/28/2017 2:31:47 PM	TEXAS INSTRUMENTS	

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